Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Approved	Checked	Designed	DEVELOPMENT SPECIFICATION				
		K. Osamo	Tentative				
			P/N : LNJ406K5YUX				

TYPE	Amber Light Emitting Diode					
APPLICATION	Indicators					
MATERIAL	GaAsP					
OUTLINE	Attached					
ABSOLUTE MAXIMUM RATINGS	P	※ I_{FP}	I_{FDC}	V_R	Topr	Tstg
	60 mW	60 mA	20 mA	4 V	-25～+85 ℃	-30～+100 ℃
CONDITION	Ta＝25±3 ℃					

Test Specification

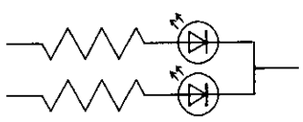
Item	Symbol	Condition	Typ	Limit		Unit
				Min	Max	
Forward Voltage	V_F	I_F=10 mA	2.0		2.6	V
Reverse Leakage Current	I_R	V_R= 4 V			10	μA
Luminous Intensity	I_O	I_F=10 mA・DC	1.0	0.4		mcd
Peak Emission Wavelength	λp	I_F=10 mA・DC	590			nm
Spectral Line Half Width	Δλ	I_F=10 mA・DC	30			nm

※ ・ The Condition of I_{FP} is duty 10 %, Pulse width 1 ms

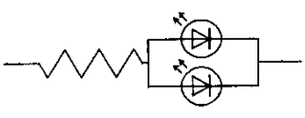
・ Please contact the Panasonic local office if you design at low current (below 1 mA DC) or pulse current operation and have any questions.

NOTE

1. Compositions of the lead … Cu/Ni/Au plating
2. Soldering conditions.
   Refer to Handling note.
3. Care should be taken that soldering is done within 3-days after opening the dry package and reel.
4. Package:Light yellow diffusion type.
5. Circuit to operate LED.



(A)



(B)

(A) Recommended circuit.
(B) The difference of brightness between the LED could be found due to the V_F characteristics of each LED.

Oct. 27. 2001			

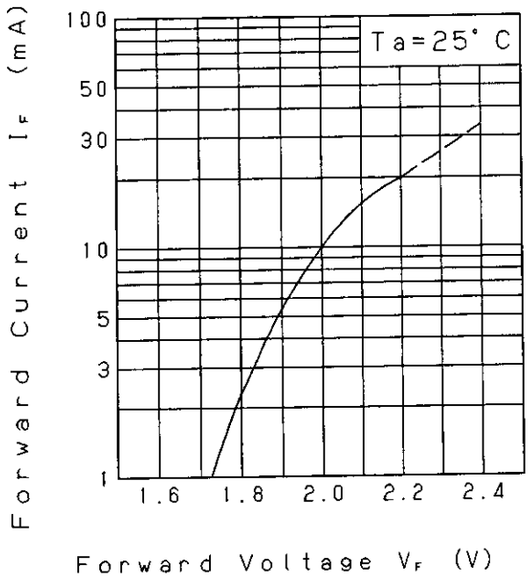
Approved	Checked	Designed
		K. Ozeki

DEVELOPMENT SPECIFICATION

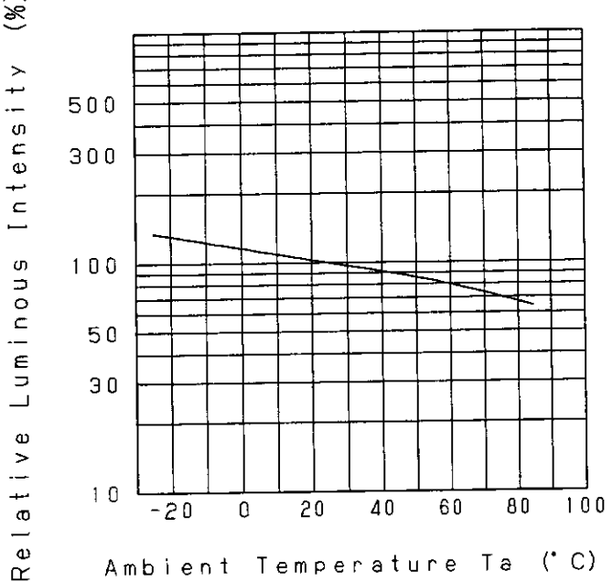
Tentative

P/N:LNJ406K5YUX

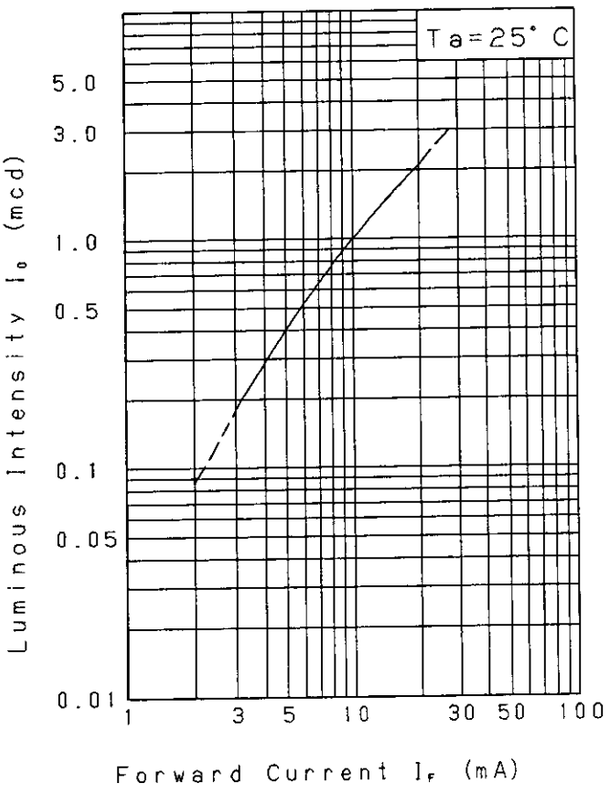
I_F - V_F



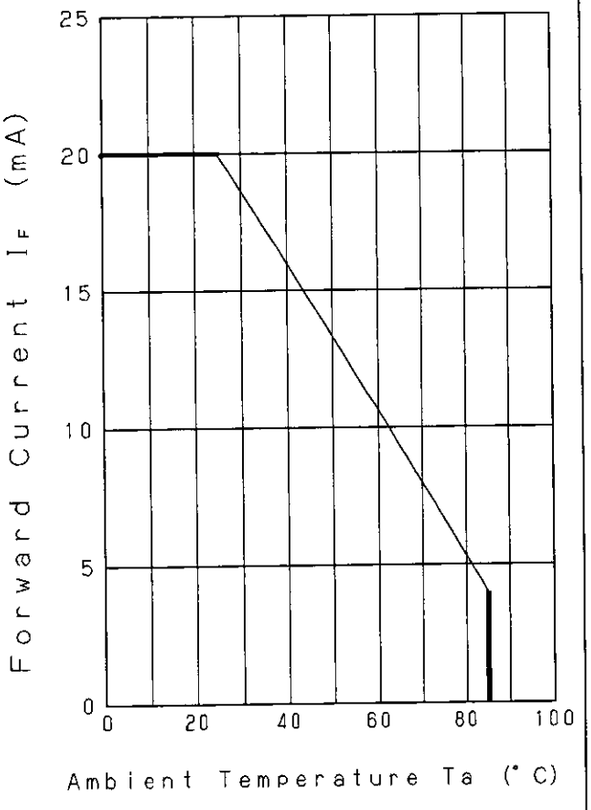
Io - Ta



Io - I_F



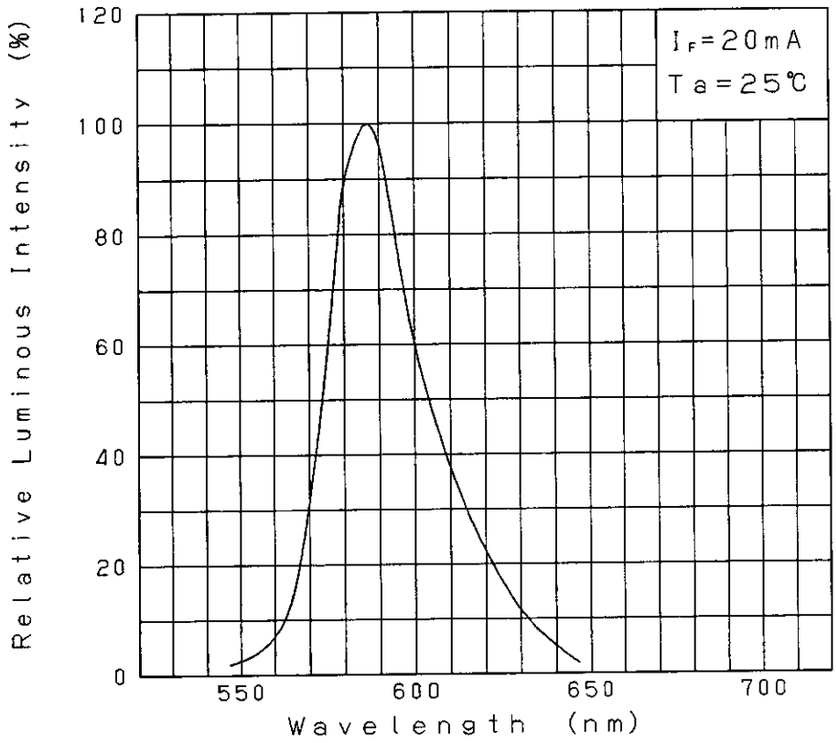
I_F - Ta



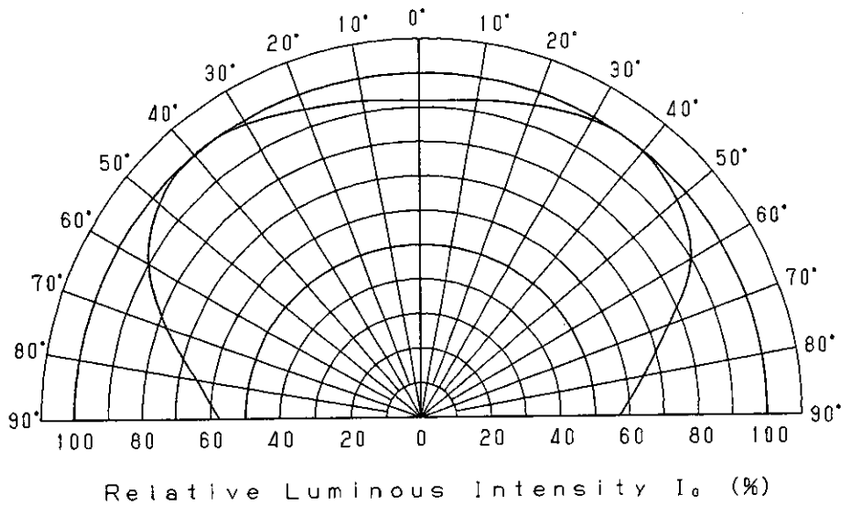
Oct.27.2001			

Approved	Checked	Designed	DEVELOPMENT SPECIFICATION Tentative P/N:LNJ406K5YUX	

Relative Luminous Intensity
Wavelength Characteristics



Derective Characteristics



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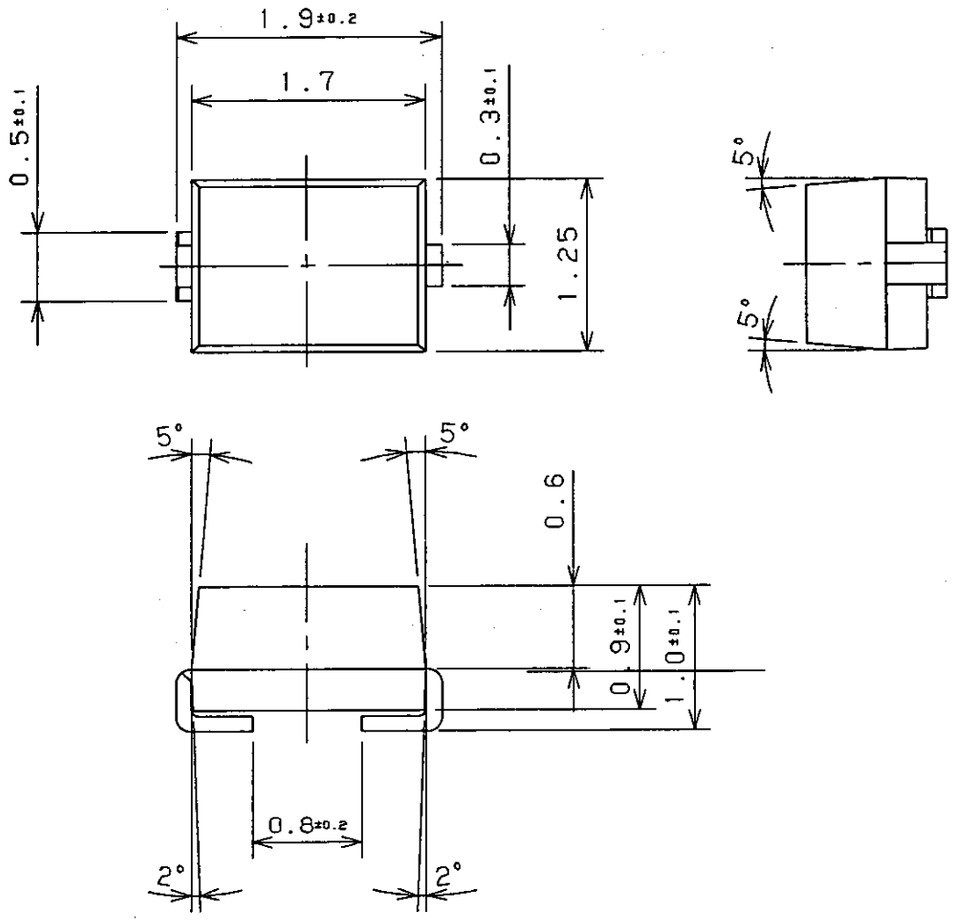
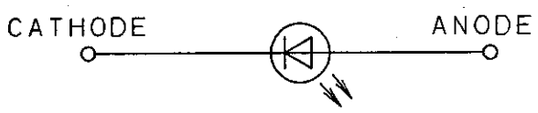
Approved	Checked	Designed

DEVELOPMENT SPECIFICATION
(OUTLINE)

P/N:





(NOTE)
1. Unit: mm
2. Tolerance unless specified is ±0.2.
3. Measurement of the Package doesn't include gete projection.
4. Corner of the package is R 0.2max.
5. Projection's tolerance of the package is R 0.2max.

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